

T-46-23-17



M421202A-APR91

DESCRIPTION

The HYM5C9256 is a 256K words by 9 bits dynamic RAM module and consists of nine HY53C256LF Fast Page mode CMOS DRAMs in 18 pin PLCC package mounted on a 30 pin glass-epoxy printed circuit board. 0.22μF decoupling capacitors are mounted under all the 256K DRAMs.

HYM5C9256M is a socket type and HYM5C9256P is a leaded type single-in-line module, these are suitable for easy interchange and addition of 256K bytes memory with parity RAM.

FEATURES

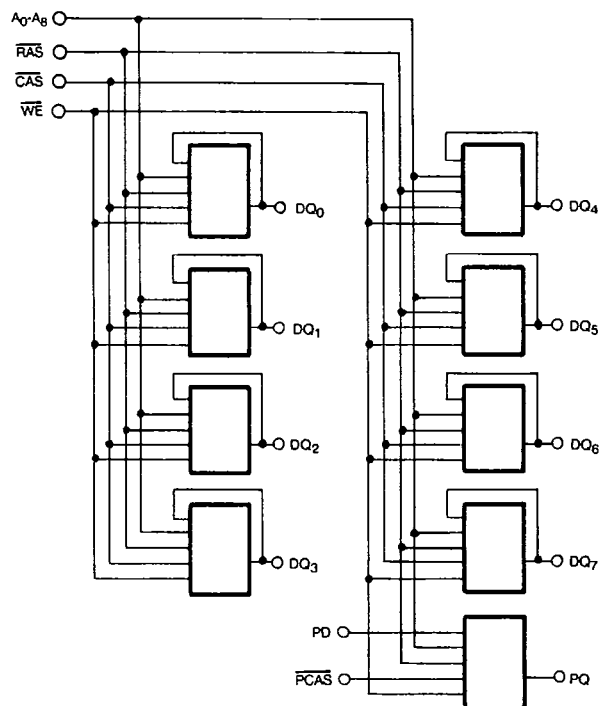
- Fast Page Mode operation
- Fast access time

	t _{RAC}	t _{CAC}	t _{PC}
HYM5C9256-70	70	15	50
HYM5C9256-80	80	20	55
HYM5C9256-100	100	25	60
HYM5C9256-120	120	30	70

- Single power supply of 5V ± 10%
- $\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$, $\overline{\text{RAS}}$ only, Hidden Refresh.
- Low power operating
 - 3.47W max.(HYM5C9256-70)
 - 2.97W max.(HYM5C9256-80)
 - 2.48W max.(HYM5C9256-100)
 - 2.23W max.(HYM5C9256-120)
- TTL compatible inputs and outputs
- 256 refresh cycles / 4ms

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BLOCK DIAGRAM

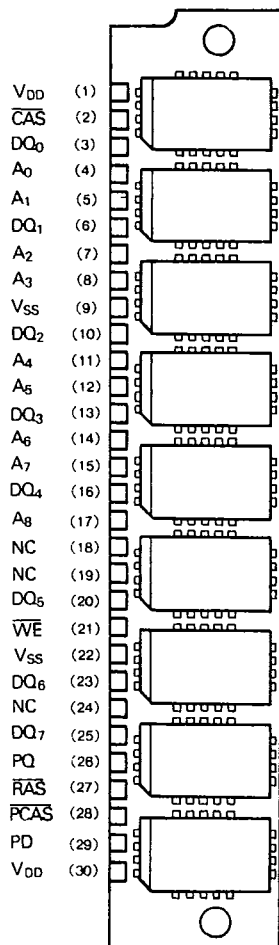


PIN NAMES

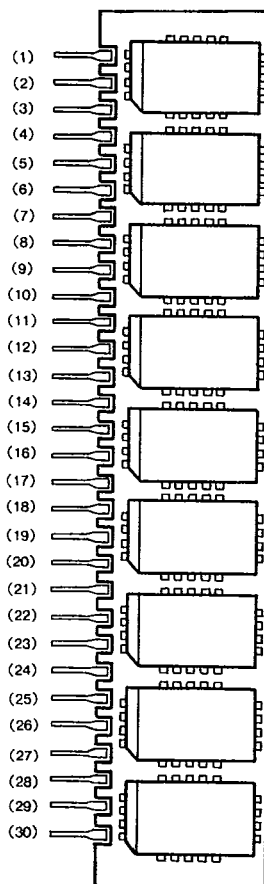
A ₀ -A ₈	ADDRESS INPUT
DQ ₀ -DQ ₇	DATA INPUT/OUTPUT
PD	DATA IN PARITY
PQ	DATA OUT FOR PARITY
$\overline{\text{RAS}}$	ROW ADDRESS STROBE
$\overline{\text{CAS}}$	COLUMN ADDRESS STROBE
$\overline{\text{PCAS}}$	$\overline{\text{CAS}}$ FOR PARITY
$\overline{\text{WE}}$	WRITE ENABLE
V _{DD}	POWER(+5V)
V _{SS}	GROUND

PIN CONNECTIONS

HYM5C9256M



HYM5C9256P



NOTES :

1. HYM5C9256P's pin configuration is the same as HYM5C9256M's.
2. Common $\overline{\text{CAS}}$ control for eight data-in and data-out lines (DQ₀-DQ₇).
3. Separate PCAS control for one separate pair of data-in (PD) and data-out (PQ) lines.
4. The common I/O feature dictates the use of only early write operations to prevent contention on data-in and data-out(DQ₀-DQ₇).

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
T_A	Ambient Temperature	0 to 70	°C
T_{STG}	Storage Temperature	-55 to 150	°C
V_{IN}, V_{OUT}	Voltage on Any Pin Relative to V_{SS}	-1.0 to 7.0	V
V_{DD}	Voltage on V_{DD} Relative to V_{SS}	-1.0 to 7.0	V
I_{OS}	Short Circuit Output Current	50	mA
P_T	Power Dissipation	9	W

NOTE : Operation at or above Absolute Maximum Ratings can adversely affect device reliability.

RECOMMENDED DC OPERATING CONDITIONS

 $(T_A = 0^\circ\text{C to } 70^\circ\text{C})$

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{DD}	Supply Voltage	4.5	5.0	5.5	V
V_{IH}	Input High Voltage	2.4	—	$V_{DD} + 1$	V
V_{IL}	Input Low Voltage	-1.0	—	0.8	V

NOTE : All voltages are reference to V_{SS} .

DC CHARACTERISTICS

 $(T_A = 0^\circ\text{C to } 70^\circ\text{C}, V_{DD} = 5V \pm 10\%, V_{SS} = 0V, \text{ unless otherwise noted.})$

SYMBOL	PARAMETER	TEST CONDITIONS	SPEED	HYM5C9256		UNIT	NOTE
				MIN.	MAX.		
$ I_{II} $	Input Leakage Current(any input pin)	$V_{SS} \leq V_{IN} \leq V_{DD}$			90	μA	
$ I_{LO} $	Output Leakage Current for High Impedance State	$V_{SS} \leq V_{OUT} \leq V_{DD}$ RAS, CAS at V_{IH}			10	μA	
I_{DD1}	V_{DD} Supply Current, Operating	$t_{RC} = t_{RC}(\text{min.})$	-70		630	mA	1, 2
			-80		540		
			-10		450		
			-12		405		
I_{DD2}	V_{DD} Supply Current, TTL Standby	RAS, CAS at V_{IH} other inputs $\geq V_{SS}$			18	mA	
I_{DD3}	V_{DD} Supply Current, RAS-only Refresh	$t_{RC} = t_{RC}(\text{min.})$	-70		630	mA	2
			-80		540		
			-10		450		
			-12		405		
I_{DD4}	V_{DD} Supply Current, Fast Page Mode	Minimum Cycle	-70		405	mA	1, 2
			-80		360		
			-10		315		
			-12		270		
I_{DD5}	V_{DD} Supply Current, CMOS Standby	RAS $\geq V_{DD} - 0.2V$, CAS = V_{IH} , other inputs $\geq V_{SS}$			9	mA	1
I_{DD6}	V_{DD} Supply Current, CAS-Before-RAS Refresh	$t_{RC} = t_{RC}(\text{min.})$	-70		630	mA	2
			-80		540		
			-10		450		
			-12		405		
V_{OL}	Output Low Voltage	$I_{OL} = 4.2\text{mA}$			0.4	V	
V_{OH}	Output High Voltage	$I_{OH} = -5\text{mA}$		2.4		V	

NOTES :

1. I_{DD} is depends on output loading when the device output is selected. Specified $I_{DD}(\text{max.})$ is measured with the output open.2. I_{DD} is depends upon the number of address transitions. Specified $I_{DD}(\text{max.})$ is measured with a maximum of two transitions per address cycle in fast page mode.

AC CHARACTERISTICS

(T_A=0°C to 70°C, V_{DD}=5V±10%, V_{SS}=0V, unless otherwise noted.)

#	SYMBOL	PARAMETER	HYM5C9256								UNIT	NOTE
			70		80		10		12			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
1	t _{RAS}	RAS Pulse Width	70	10K	80	10K	100	10K	120	10K	ns	
2	t _{RC}	Read or Write Cycle Time	130		145		175		205		ns	
3	t _{RP}	RAS Precharge Time	50		55		65		75		ns	
4	t _{ASR}	Row Address Set-up Time	0		0		0		0		ns	
5	t _{RAH}	Row Address Hold Time	15		15		15		20		ns	
6	t _{RAI}	Column Address to RAS Lead Time	35		40		45		55		ns	
7	t _{RAD}	RAS to Column Address Delay Time	20	35	20	40	20	55	25	65	ns	1
8	t _{ASC}	Column Address Set-up Time	0		0		0		0		ns	
9	t _{CAH}	Column Address Hold Time	15		15		20		25		ns	
10	t _{RCD}	RAS to CAS Delay	25	55	25	60	25	75	30	90	ns	2
11	t _{RAC}	Access Time from RAS		70		80		100		120	ns	3,4,5
12	t _{AA}	Access Time From Column Address		35		40		45		55	ns	5,6,12
13	t _{CAC}	Access Time from CAS		15		20		25		30	ns	5,12
14	t _{CAS}	CAS Pulse Width	15	75K	20	75K	25	75K	30	75K	ns	
15	t _{RSH}	RAS Hold Time	15		20		25		30		ns	
16	t _{RCS}	Read Command Set-up Time	0		0		0		0		ns	
17	t _{RCH}	Read Command Hold Time Referenced to CAS	5		5		5		5		ns	7
18	t _{RRH}	Read Command Hold Time Referenced to RAS	5		5		5		5		ns	7
19	t _{CRP}	CAS to RAS Precharge Time	15		15		15		20		ns	
20	t _{OFF}	Output Buffer Turn Off Delay	0	15	0	20	0	25	0	30	ns	8
21	t _{WP}	Write Command Pulse Width	15		15		20		25		ns	
22	t _{CP}	CAS Precharge Time	15		15		20		25		ns	
23	t _{AR}	Column Address Hold Time From RAS	55		60		70		80		ns	
24	t _{WCR}	Write Command Hold Time From RAS	55		60		70		80		ns	
25	t _{WCS}	Write Command Set-up Time	0		0		0		0		ns	9,10
26	t _{WCH}	Write Command Hold Time	15		15		20		25		ns	
27	t _{DS}	Data In Set-up Time	0		0		0		0		ns	11
28	t _{DH}	Data In Hold Time	15		15		20		25		ns	11
29	t _{DHR}	Data In Hold Time Reference to RAS	55		60		70		80		ns	
30	t _{CPA}	Access Time from CAS Precharge		45		50		55		65	ns	12

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#	SYMBOL	PARAMETER	HYM5C9256								UNIT	NOTE
			70		80		10		12			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
31	t _{PC}	Fast Page Mode Cycle time	50		55		60		70		ns	
32	t _{RWL}	Write Command to $\overline{\text{RAS}}$ Lead Time	20		25		30		35		ns	
33	t _{CWL}	Write Command to $\overline{\text{CAS}}$ Lead Time	20		25		30		35		ns	
34	t _{RPC}	$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Precharge Time	0		0		0		0		ns	
35	t _{CSR}	$\overline{\text{CAS}}$ Set-up Time, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh	10		10		10		10		ns	
36	t _{CHR}	$\overline{\text{CAS}}$ Hold Time, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh	20		25		30		40		ns	
37	t _T	Transition Time(Rise and Fall)	3	25	3	25	3	25	3	25	ns	
38	t _{REF}	Refresh Interval(256 cycle)		4		4		4		4	ms	

NOTES:

- Operation within the t_{RAD}(max.) limit insures that t_{RAC}(max.) can be met. t_{RAD}(max.) is specified as a referenced point only. If t_{RAD} is greater than the specified t_{RAD}(max.) limit, then the access time is controlled by t_{AA} and t_{CAC}.
- Operation within the t_{RCD}(max.) limit insures that t_{RAC}(max.) can be met. t_{RCD}(max.) is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD}(max.) limit, then the access time is controlled by t_{CAC}.
- Assume t_{RAD} ≤ t_{RAD}(max.). If t_{RAD} is greater than t_{RAD}(max.) then t_{RAC} will increase by the amount that t_{RAD} exceeds t_{RAD}(max.).
- Assume t_{RCD} ≤ t_{RCD}(max.). If t_{RCD} is greater than t_{RCD}(max.) then t_{RAC} will increase by the amount that t_{RCD} exceeds t_{RCD}(max.).
- Measured with a load equivalent to two TTL loads and 100 pF.
- Assumes that t_{RCD} ≥ t_{RCD}(max.) and t_{RAD} ≤ t_{RAD}(max.).
- Assumes that t_{RCD} ≤ t_{RCD}(max.) and t_{RAD} ≥ t_{RAD}(max.).
- Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
- t_{OFF} define the time at which the data output achieves the open circuit condition and is not referenced to the output voltage levels.
- t_{WCS} is not a restrictive operating parameter. This is included in the data sheet as a electrical characteristic only. If t_{WCS} ≥ t_{WCS}(min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle.
- t_{DS} and t_{DH} are referenced to the latter occurrence of $\overline{\text{CAS}}$ or $\overline{\text{WE}}$.
- Access time is determined by the longer of t_{AA}, t_{CAC}, t_{CPA}.
- t_T is measured between V_{IH}(min.) and V_{IL}(max.).
- AC measurements assume t_T = 5ns.
- An initial pause of 200μs is required after power-up and followed by at least 8 initialization cycles (any combination of cycles containing a $\overline{\text{RAS}}$ clock such as $\overline{\text{RAS}}$ -only refresh). 8 initialization cycles are required after extended period of bias without clocks.

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CAPACITANCE

(T_A = 25°C, V_{DD} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted.)

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
C _{IN1}	Input Capacitance(A ₀ -A ₈ , $\overline{\text{WE}}$, $\overline{\text{CAS}}$, $\overline{\text{RAS}}$)	—	60	pF
C _{IN2}	Input Capacitance(PD, $\overline{\text{PCAS}}$)	—	10	pF
C _{DQ}	I/O Capacitance(DQ ₀ -DQ ₇)	—	15	pF
C _{PQ}	Output Capacitance(PQ)	—	10	pF

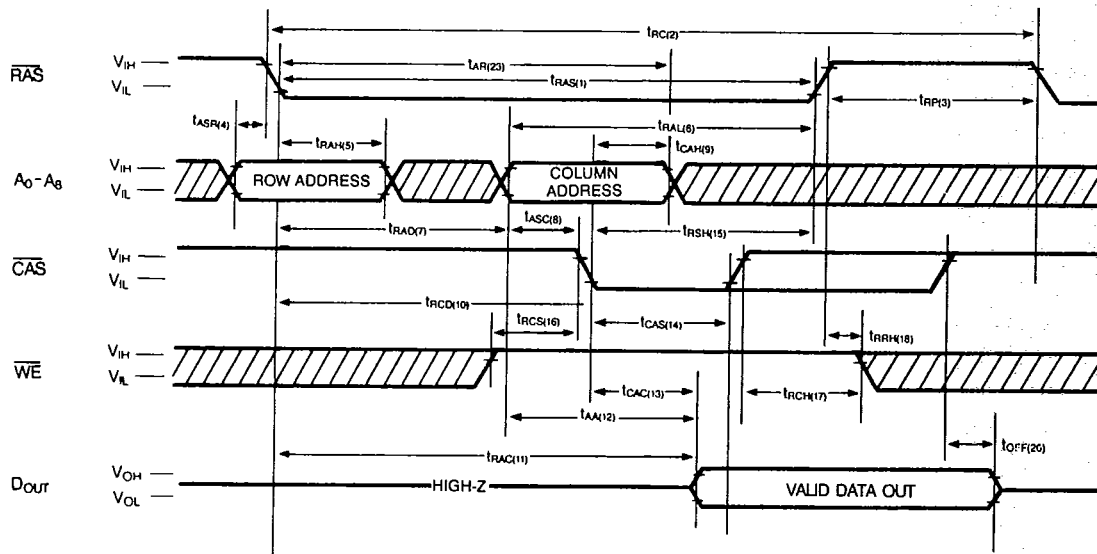
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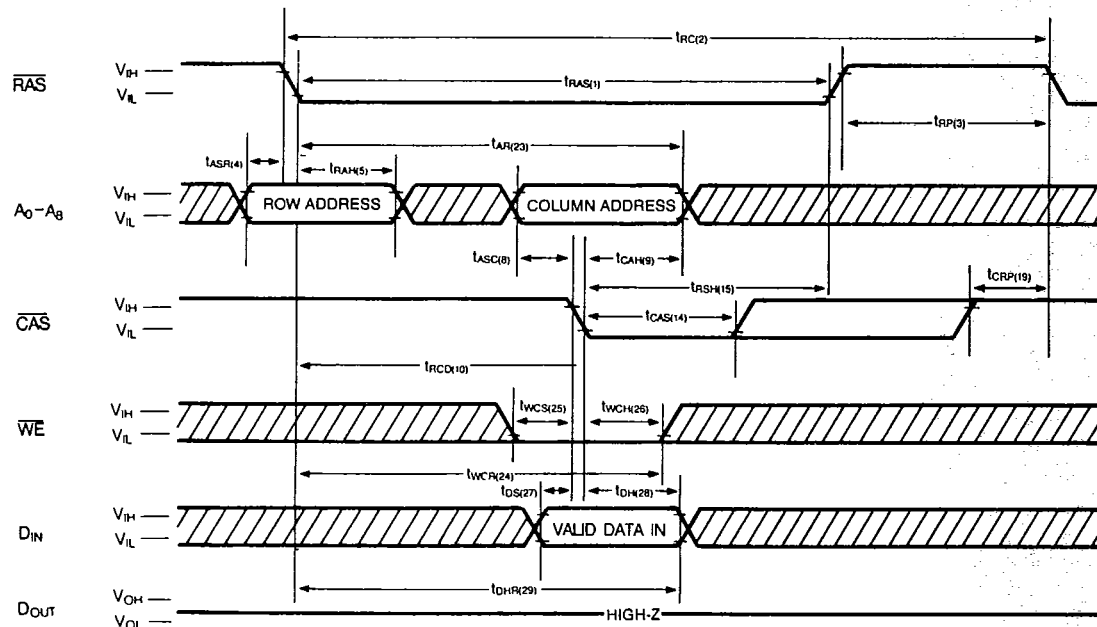
TIMING DIAGRAM

(CAS includes PCAS and CAS, D_{IN} includes DQ_0-DQ_7 and PD, D_{OUT} includes DQ_0-DQ_7 and PQ.)

READ CYCLE



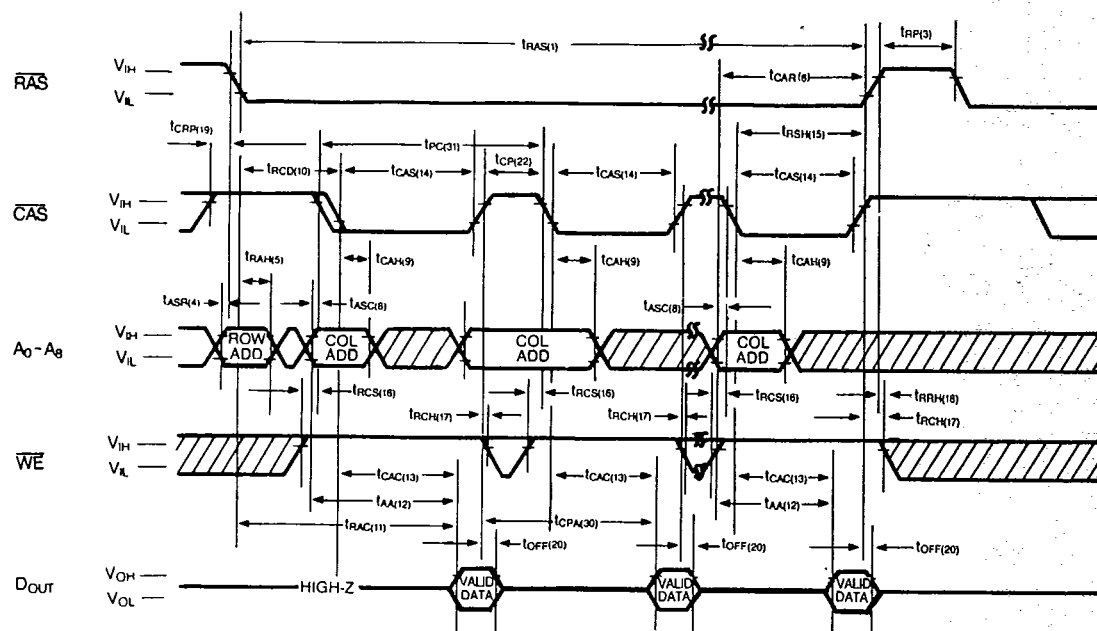
EARLY WRITE CYCLE



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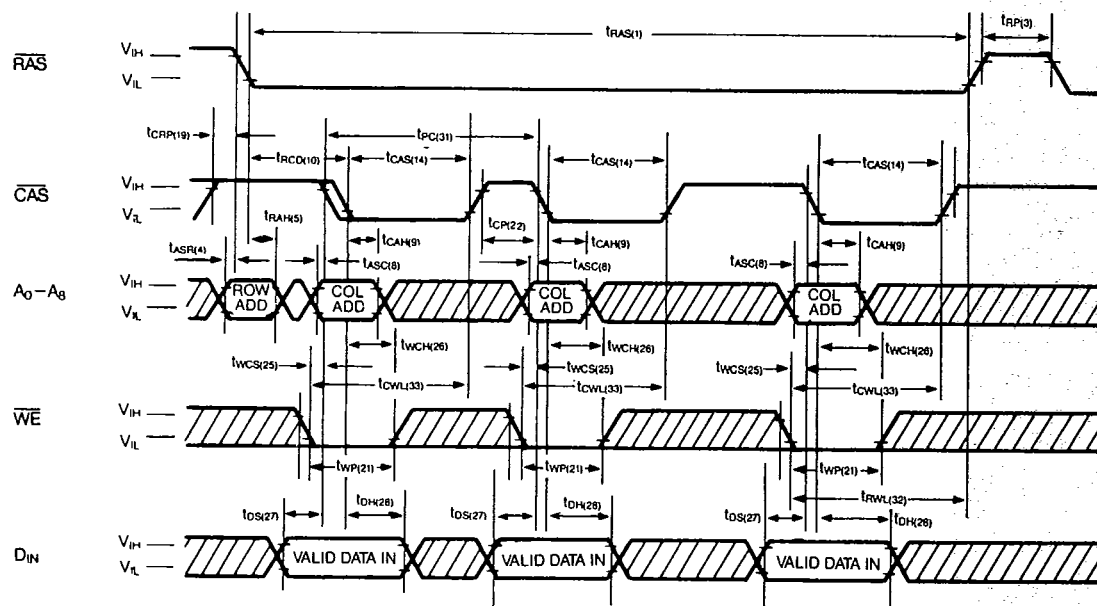
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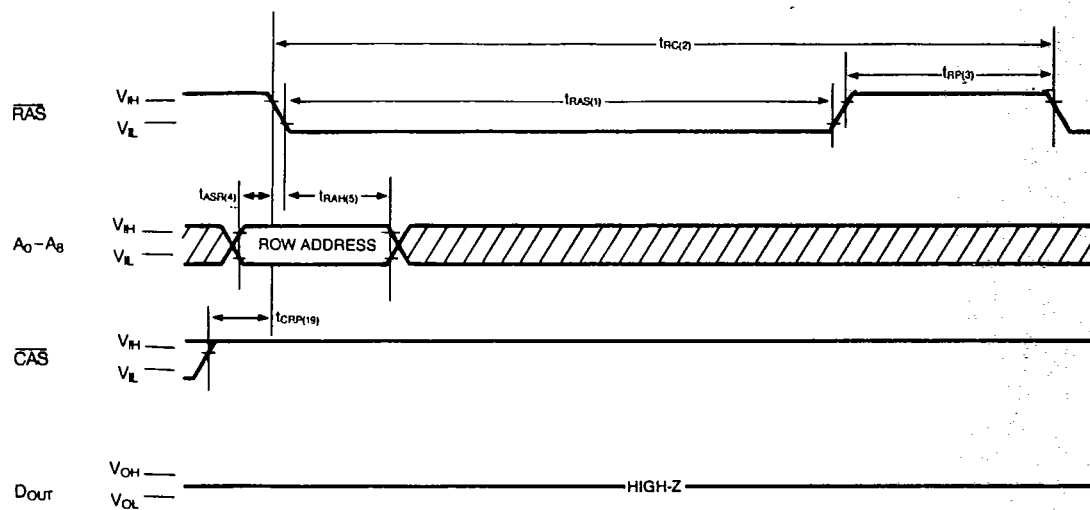
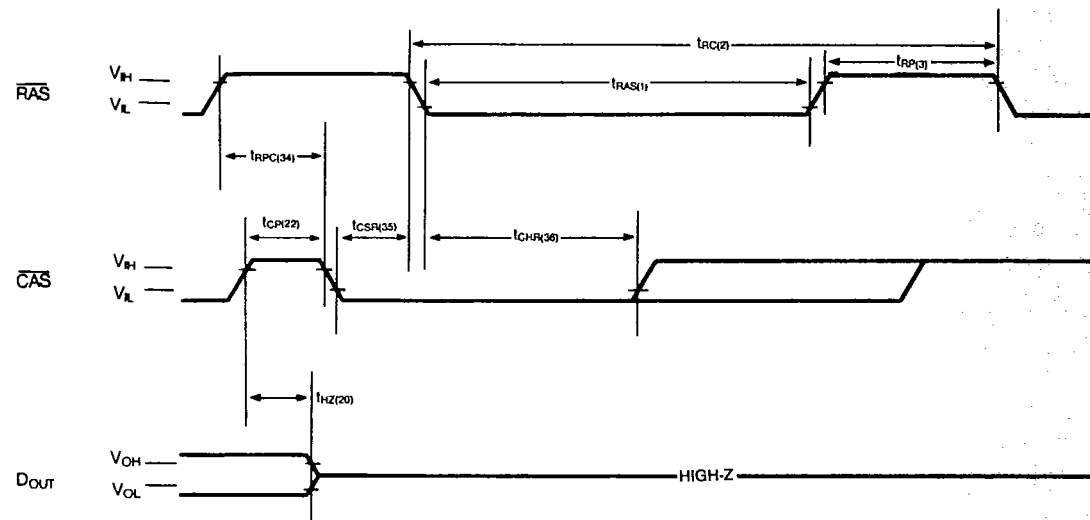
FAST PAGE MODE READ CYCLE



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FAST PAGE MODE EARLY WRITE CYCLE

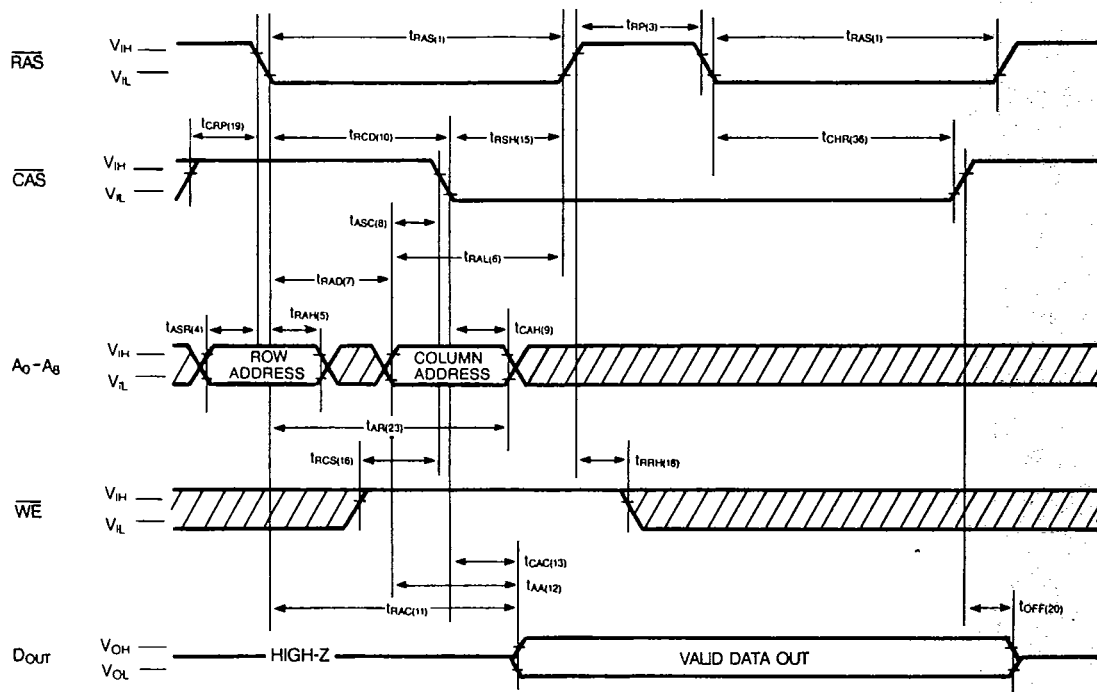


RAS-ONLY REFRESH CYCLE**CAS-BEFORE-RAS REFRESH CYCLE**

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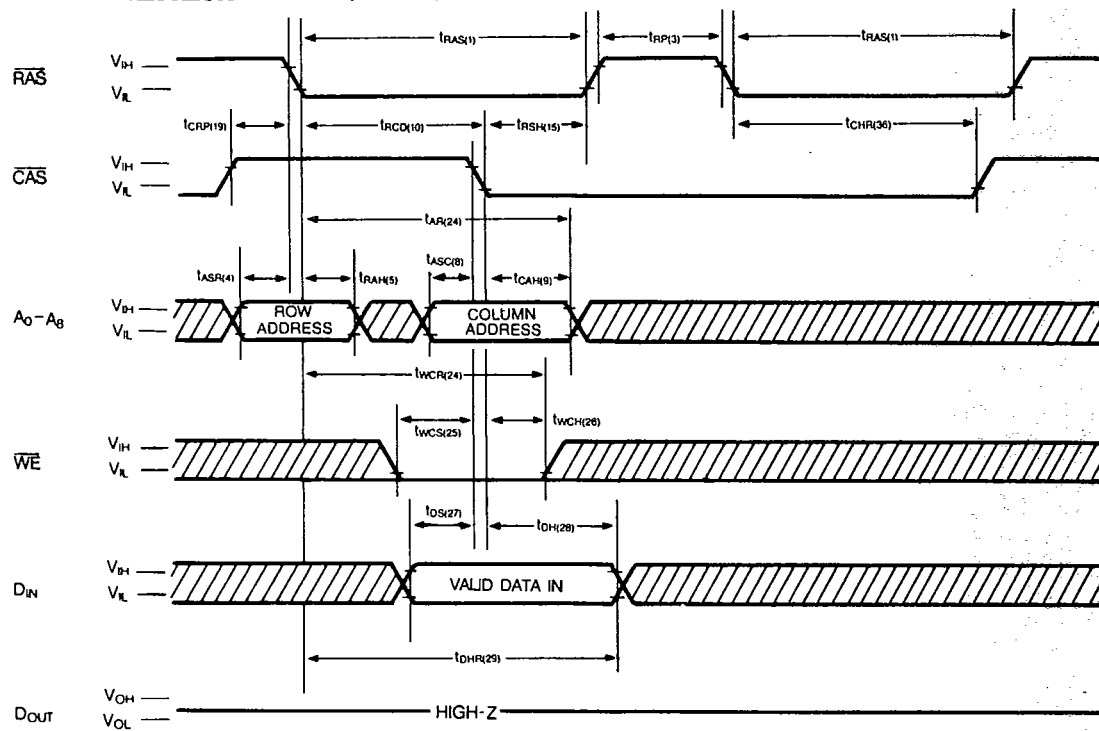
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HIDDEN REFRESH CYCLE (READ)



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HIDDEN REFRESH CYCLE (WRITE)



CAS-BEFORE-RAS REFRESH COUNTER TEST CYCLE